

# DS91M040 125 MHz Quad M-LVDS Transceiver

## **General Description**

The DS91M040 is a quad M-LVDS transceiver designed for driving / receiving clock or data signals to / from up to four multipoint networks.

M-LVDS (Multipoint LVDS) is a new family of bus interface devices based on LVDS technology specifically designed for multipoint and multidrop cable and backplane applications. It differs from standard LVDS in providing increased drive current to handle double terminations that are required in multipoint applications. Controlled transition times minimize reflections that are common in multipoint configurations due to unterminated stubs. M-LVDS devices also have a very large input common mode voltage range for additional noise margin in heavily loaded and noisy backplane environments.

A single DS91M040 channel is a half-duplex transceiver that accepts LVTTL/LVCMOS signals at the driver inputs and converts them to differential M-LVDS signal levels. The receiver inputs accept low voltage differential signals (LVDS, BLVDS, M-LVDS, LVPECL and CML) and convert them to 3V LVC-MOS signals. The DS91M040 supports both M-LVDS type 1 and type 2 receiver inputs.

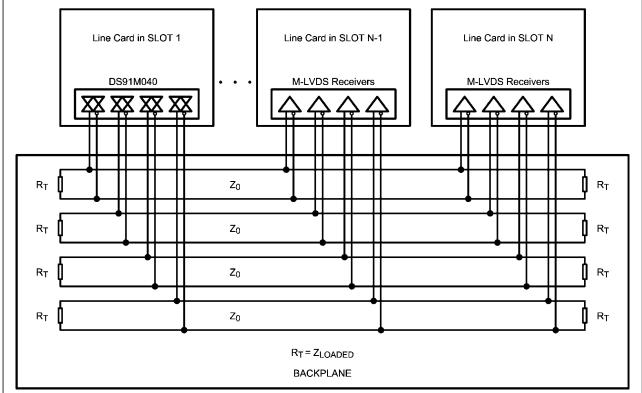
#### **Features**

- DC 125 MHz / 250 Mbps low jitter, low skew, low power operation
- Wide Input Common Mode Voltage Range allows up to ±2V of GND noise
- Conforms to TIA/EIA-899 M-LVDS Standard
- Pin selectable M-LVDS receiver type (1 or 2)
- Controlled transition times (2.0 ns typ) minimize reflections
- 8 kV ESD on M-LVDS I/O pins protects adjoining components
- Flow-through pinout simplifies PCB layout
- Small 5 mm x 5 mm LLP-32 space saving package

#### **Applications**

- Multidrop / Multipoint clock and data distribution
- High-Speed, Low Power, Short-Reach alternative to TIA/ EIA-485/422
- Clock distribution in AdvancedTCA (ATCA) and MicroTCA (μTCA) backplanes

## **Typical Application**

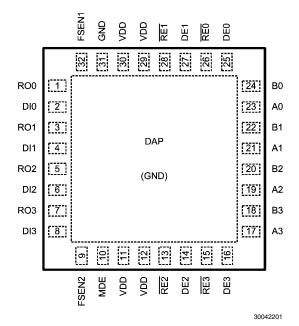


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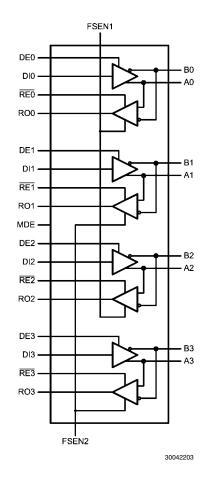
# **Ordering Information**

Order Number	Receiver Input	Function	Package Type
DS91M040TSQ	Type 1 or 2	Quad M-LVDS Transciever	LLP-32

# **Connection Diagram**



# **Logic Diagram**



# **Pin Descriptions**

Number	Name	I/O, Type	Description	
1, 3, 5, 7	RO	O, LVCMOS	Receiver output pin.	
26, 28, 13, 15	RE	I, LVCMOS	Receiver enable pin: When RE is high, the receiver is disabled.	
			When $\overline{RE}$ is low, the receiver is enabled. There is a 300 k $\Omega$ pull	
			resistor on this pin.	
25, 27, 14, 16	DE	I, LVCMOS	Driver enable pin: When DE is low, the driver is disabled. When	
			DE is high, the driver is enabled. There is a 300 $k\Omega$ pulldown	
			resistor on this pin.	
2, 4, 6, 8	DI	I, LVCMOS	Driver input pin.	
31, DAP	GND	Power	Ground pin and pad.	
17, 19, 21, 23	Α	I/O, M-LVDS	Non-inverting driver output pin/Non-inverting receiver input pin	
18, 20, 22, 24	В	I/O, M-LVDS	Inverting driver output pin/Inverting receiver input pin	
11, 12, 29, 30	$V_{DD}$	Power	Power supply pin, +3.3V ± 0.3V	
32	FSEN1	I, LVCMOS	Failsafe enable pin with a 300 k $\Omega$ pullup resistor. This pin	
			enables Type 2 receiver on inputs 0 and 2.	
			FSEN1 = L> Type 1 receiver inputs	
			FSEN1 = H> Type 2 receiver inputs	
9	FSEN2	I, LVCMOS	Failsafe enable pin with a 300 k $\Omega$ pullup resistor. This pin	
			enables Type 2 receiver on inputs 1 and 3.	
			FSEN2 = L> Type 1 receiver inputs	
			FSEN2 = H> Type 2 receiver inputs	
10	MDE	I, LVCMOS	Master enable pin. When MDE is H, the device is powered up.	
			When MDE is L, the device overrides all other control and powers	
			down.	

## **M-LVDS Receiver Types**

The EIA/TIA-899 M-LVDS standard specifies two different types of receiver input stages. A type 1 receiver has a conventional threshold that is centered at the midpoint of the input amplitude,  $V_{\text{ID}}/2$ . A type 2 receiver has a built in offset that is 100mV greater then  $V_{\text{ID}}/2$ . The type 2 receiver offset acts as a failsafe circuit where open or short circuits at the input will always result in the output stage being driven to a low logic state.

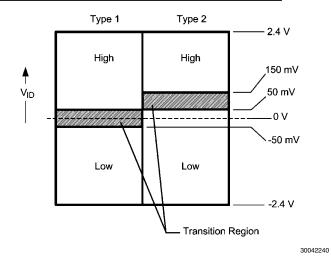


FIGURE 1. M-LVDS Receiver Input Thresholds

### **Absolute Maximum Ratings** (Note 4)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Power Supply Voltage -0.3V to +4V LVCMOS Input Voltage -0.3V to  $(V_{DD} + 0.3V)$  LVCMOS Output Voltage -0.3V to  $(V_{DD} + 0.3V)$  M-LVDS I/O Voltage -5.5V to +5.5V

M-LVDS Output Short Circuit

Current Duration Continuous

Junction Temperature +140°C

Storage Temperature Range -65°C to +150°C

Lead Temperature Range

Soldering (4 sec.) +260°C

Maximum Package Power Dissipation @ +25°C

SQ Package 833 mW

Derate SQ Package 6.67 mW/°C above +25°C

Package Thermal Resistance

 $\theta_{JA}$  +150°C/W  $\theta_{JC}$  +63.8°C/W

ESD Susceptibility

HBM (Note 1) ≥8 kV

MM (Note 2) ≥250V

CDM (Note 3) ≥1250V

Note 1: Human Body Model, applicable std. JESD22-A114C
Note 2: Machine Model, applicable std. JESD22-A115-A
Note 3: Field Induced Charge Device Model, applicable std.
JESD22-C101-C

# Recommended Operating Conditions

	Min	Тур	Max	Units
Supply Voltage, V <sub>DD</sub>	3.0	3.3	3.6	V
Voltage at Any Bus Terminal	-1.4		+3.8	V
(Separate or Common-Mode)				
Differential Input Voltage $V_{\rm ID}$			2.4	V
LVTTL Input Voltage High $V_{\rm IH}$	2.0		$V_{DD}$	V
LVTTL Input Voltage Low V <sub>IL</sub>	0		8.0	V
Operating Free Air				
Temperature T <sub>A</sub>	-40	+25	+85	°C

## DC Electrical Characteristics (Notes 5, 6, 7, 9)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Units
M-LVDS D	river						
IV <sub>AB</sub> I	Differential output voltage magnitude	$R_L = 50\Omega, C_L = 5 pF$		480		650	mV
$\Delta V_{AB}$	Change in differential output voltage magnitude between logic states	Figures 2, 4		-50	0	+50	mV
V <sub>OS(SS)</sub>	Steady-state common-mode output voltage	$R_L = 50\Omega$ , $C_L = 5 pF$		0.3	1.6	2.1	٧
$ \Delta V_{OS(SS)} $	Change in steady-state common-mode output voltage between logic states	Figures 2, 3		0		+50	mV
V <sub>A(OC)</sub>	Maximum steady-state open-circuit output voltage	Figure 5		0		2.4	V
V <sub>B(OC)</sub>	Maximum steady-state open-circuit output voltage			0		2.4	V
V <sub>P(H)</sub>	Voltage overshoot, low-to-high level output (Note 12)	$R_L = 50\Omega$ , $C_L = 5pF$ , $C_D = 0.5 pF$ Figures 7, 8				1.2V <sub>SS</sub>	V
V <sub>P(L)</sub>	Voltage overshoot, high-to-low level output (Note 12)			-0.2V <sub>S</sub>			V
I <sub>IH</sub>	High-level input current (LVTTL inputs)	V <sub>IH</sub> = 2.0V		-15		15	μΑ
I <sub>IL</sub>	Low-level input current (LVTTL inputs)	$V_{IL} = 0.8V$		-15		15	μΑ
V <sub>CL</sub>	Input Clamp Voltage (LVTTL inputs)	I <sub>IN</sub> = -18 mA		-1.5			V
I <sub>os</sub>	Differential short-circuit output current (Note 8)	Figure 6		-43		43	mA
M-LVDS R	eceiver						
V <sub>IT+</sub>	Positive-going differential input voltage threshold	See Function Tables	Type 1		16	50	mV
			Type 2		100	150	mV
V <sub>IT-</sub>	Negative-going differential input voltage threshold	See Function Tables	Type 1	-50	20		mV
		Type 2		50	94		mV
$V_{OH}$	High-level output voltage (LVTTL output)	$I_{OH} = -8mA$		2.4	2.7		V
V <sub>OL</sub>	Low-level output voltage (LVTTL output)	I <sub>OL</sub> = 8mA			0.28	0.4	٧
I <sub>OZ</sub>	TRI-STATE output current	V <sub>O</sub> = 0V or 3.6V		-10		10	μΑ
I <sub>OSR</sub>	Short-circuit receiver output current (LVTTL output)	V <sub>O</sub> = 0V			-50	-90	mA

Symbol	Parameter	Conditions	Min	Тур	Max	Units				
M-LVDS B	M-LVDS Bus (Input and Output) Pins									
I <sub>A</sub>	Transceiver input/output current	$V_A = 3.8V, V_B = 1.2V$			32	μA				
		$V_A = 0V \text{ or } 2.4V, V_B = 1.2V$	-20		+20	μA				
		$V_A = -1.4V, V_B = 1.2V$	-32			μΑ				
I <sub>B</sub>	Transceiver input/output current	$V_B = 3.8V, V_A = 1.2V$			32	μA				
		$V_B = 0V \text{ or } 2.4V, V_A = 1.2V$	-20		+20	μA				
		$V_B = -1.4V, V_A = 1.2V$	-32			μA				
I <sub>AB</sub>	Transceiver input/output differential current $(I_A - I_B)$	$V_A = V_B, -1.4V \le V \le 3.8V$	-4		+4	μA				
I <sub>A(OFF)</sub>	Transceiver input/output power-off current	$V_A = 3.8V, V_B = 1.2V,$ DE = $V_{CC} = 1.5V$			32	μΑ				
		$V_A = 0V \text{ or } 2.4V, V_B = 1.2V, $ DE = $V_{CC} = 1.5V$	-20		+20	μΑ				
		$V_A = -1.4V, V_B = 1.2V,$ DE = $V_{CC} = 1.5V$	-32			μA				
I <sub>B(OFF)</sub>	Transceiver input/output power-off current	$V_B = 3.8V, V_A = 1.2V,$ DE = $V_{CC} = 1.5V$			32	μА				
		$V_B = 0V \text{ or } 2.4V, V_A = 1.2V,$ DE = $V_{CC} = 1.5V$	-20		+20	μA				
		$V_B = -1.4V, V_A = 1.2V,$ DE = $V_{CC} = 1.5V$	-32			μA				
I <sub>AB(OFF)</sub>	Transceiver input/output power-off differential current $(I_{A(OFF)} - I_{B(OFF)})$	$V_A = V_B, -1.4V \le V \le 3.8V,$ $V_{DD} = 1.5V, DE = 1.5V$	-4		+4	μA				
C <sub>A</sub>	Transceiver input/output capacitance	V <sub>DD</sub> = OPEN		7.8		pF				
C <sub>B</sub>	Transceiver input/output capacitance			7.8		pF				
C <sub>AB</sub>	Transceiver input/output differential capacitance			3		pF				
C <sub>A/B</sub>	Transceiver input/output capacitance balance ( $C_A$ / $C_B$ )			1						
SUPPLY C	CURRENT (V <sub>CC</sub> )		•							
I <sub>CCD</sub>	Driver Supply Current	$R_L = 50\Omega$ , $DE = H$ , $\overline{RE} = H$		67	75	mA				
I <sub>ccz</sub>	TRI-STATE Supply Current	DE = L, RE = H		22	26	mA				
I <sub>CCR</sub>	Receiver Supply Current	DE = L, RE = L		32	38	mA				
I <sub>CCPD</sub>	Power Down Supply Current	MDE = L		3	5	mA				

Note 4: "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions at which the device is functional and the device should not be operated beyond such conditions.

Note 5: The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 6: Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except  $V_{OD}$  and  $\Delta V_{OD}$ .

Note 7: Typical values represent most likely parametric norms for  $V_{DD} = +3.3V$  and  $T_A = +25^{\circ}C$ , and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

 $\textbf{Note 8:} \ \text{Output short circuit current ($I_{OS}$) is specified as magnitude only, minus sign indicates direction only.}$ 

Note 9:  $C_L$  includes fixture capacitance and  $C_D$  includes probe capacitance.

#### **Switching Characteristics** (Notes 10, 11, 17)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
DRIVER AC	SPECIFICATIONS		<u> </u>	,	,	
t <sub>PLH</sub>	Differential Propagation Delay Low to High	$R_L = 50\Omega, C_L = 5 pF,$	1.5	3.3	5.5	ns
t <sub>PHL</sub>	Differential Propagation Delay High to Low	C <sub>D</sub> = 0.5 pF	1.5	3.3	5.5	ns
t <sub>SKD1</sub>	Pulse Skew (Notes 12, 13)	Figures 7, 8		30	125	ps
t <sub>SKD2</sub>	Channel-to-Channel Skew (Notes 12, 14)			100	200	ps
t <sub>SKD3</sub>	Part-to-Part Skew (Notes 12, 15)			0.8	1.6	ns
t <sub>SKD4</sub>	Part-to-Part Skew (Notes 12, 16)				4	ns
t <sub>TLH</sub>	Rise Time (Note 12)		1.2	2.0	3.0	ns
t <sub>THL</sub>	Fall Time (Note 12)		1.2	2.0	3.0	ns
t <sub>PZH</sub>	Enable Time (Z to Active High)	$R_L = 50\Omega, C_L = 5 pF,$		7.5	11.5	ns
t <sub>PZL</sub>	Enable Time (Z to Active Low)	C <sub>D</sub> = 0.5 pF		8.0	11.5	ns
t <sub>PLZ</sub>	Disable Time (Active Low to Z)	Figures 9, 10		7.0	11.5	ns
t <sub>PHZ</sub>	Disable Time (Active High to Z)			7.0	11.5	ns
RECEIVER A	AC SPECIFICATIONS	•	,			
t <sub>PLH</sub>	Propagation Delay Low to High	C <sub>L</sub> = 15 pF	1.5	3.0	4.5	ns
t <sub>PHL</sub>	Propagation Delay High to Low	Figures 11, 12, 13	1.5	3.1	4.5	ns
t <sub>SKD1A</sub>	Pulse Skew (Receiver Type 1) (Notes 12, 13)			55	325	ps
t <sub>SKD1B</sub>	Pulse Skew (Receiver Type 2) (Notes 12, 13)			475	800	ps
t <sub>SKD2</sub>	Channel-to-Channel Skew (Notes 12, 14)			60	300	ps
t <sub>SKD3</sub>	Part-to-Part Skew (Notes 12, 15)			0.6	1.2	ns
t <sub>SKD4</sub>	Part-to-Part Skew (Notes 12, 16)				3	ns
t <sub>TLH</sub>	Rise Time (Note 12)		0.3	1.1	1.6	ns
t <sub>THL</sub>	Fall Time (Note 12)		0.3	0.65	1.6	ns
t <sub>PZH</sub>	Enable Time (Z to Active High)	$R_L = 500\Omega, C_L = 15 pF$		3	5.5	ns
t <sub>PZL</sub>	Enable Time (Z to Active Low)	Figures 14, 15		3	5.5	ns
t <sub>PLZ</sub>	Disable Time (Active Low to Z)			3.5	5.5	ns
t <sub>PHZ</sub>	Disable Time (Active High to Z)			3.5	5.5	ns
GENERIC AC	SPECIFICATIONS		•			
t <sub>WKUP</sub>	Wake Up Time (Note 12) (Master Device Enable (MDE) time)				500	ms
f <sub>MAX</sub>	Maximum Operating Frequency (Note 12)		125			MHz

Note 10: The Electrical Characteristics tables list guaranteed specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 11: Typical values represent most likely parametric norms for  $V_{DD} = +3.3V$  and  $T_A = +25^{\circ}C$ , and at the Recommended Operation Conditions at the time of product characterization and are not guaranteed.

Note 12: Specification is guaranteed by characterization and is not tested in production.

Note 13: t<sub>SKD1</sub>, lt<sub>PLHD</sub> – t<sub>PHLD</sub>|, Pulse Skew, is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.

 $\textbf{Note 14:} \ \textbf{t}_{SKD2}, \textbf{Channel-to-Channel Skew, is the difference in propagation delay} \ \textbf{(} \textbf{t}_{PLHD} \text{ or } \textbf{t}_{PHLD}) \text{ among all output channels.}$ 

Note 15: t<sub>SKD3</sub>, Part-to-Part Skew, is defined as the difference between the minimum and maximum differential propagation delays. This specification applies to devices at the same V<sub>DD</sub> and within 5°C of each other within the operating temperature range.

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Note 16:  $t_{SKD4}$ , Part-to-Part Skew, is the differential channel-to-channel skew of any event between devices. This specification applies to devices over recommended operating temperature and voltage ranges, and across process distribution.  $t_{SKD4}$  is defined as IMax – MinI differential propagation delay.

Note 17:  $C_L$  includes fixture capacitance and  $C_D$  includes probe capacitance.

Note 18: Measured on a clock edge with a histogram and an acummulation of 1500 histogram hits. Input stimulus jitter is subracted geometrically.

## **Test Circuits and Waveforms**

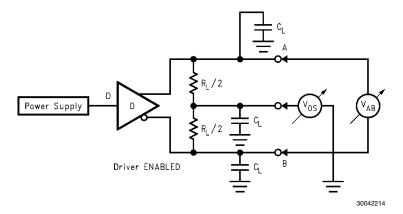
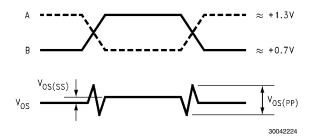


FIGURE 2. Differential Driver Test Circuit



**FIGURE 3. Differential Driver Waveforms** 

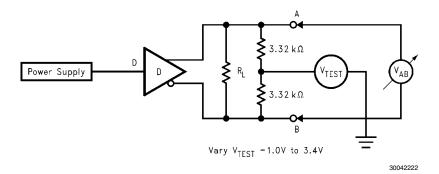


FIGURE 4. Differential Driver Full Load Test Circuit

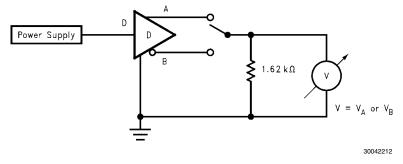


FIGURE 5. Differential Driver DC Open Test Circuit

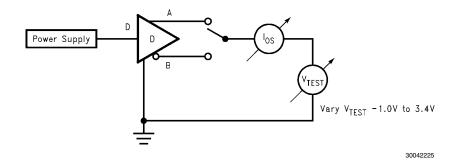


FIGURE 6. Differential Driver Short-Circuit Test Circuit

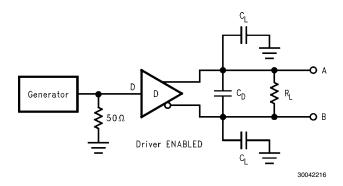


FIGURE 7. Driver Propagation Delay and Transition Time Test Circuit

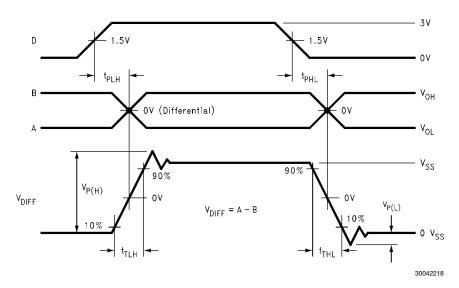


FIGURE 8. Driver Propagation Delays and Transition Time Waveforms

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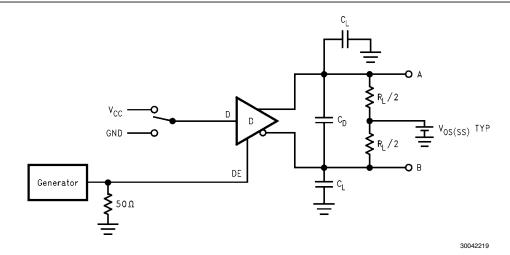


FIGURE 9. Driver TRI-STATE Delay Test Circuit

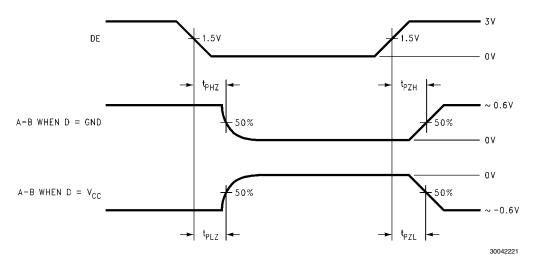


FIGURE 10. Driver TRI-STATE Delay Waveforms

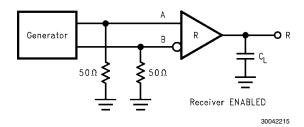


FIGURE 11. Receiver Propagation Delay and Transition Time Test Circuit

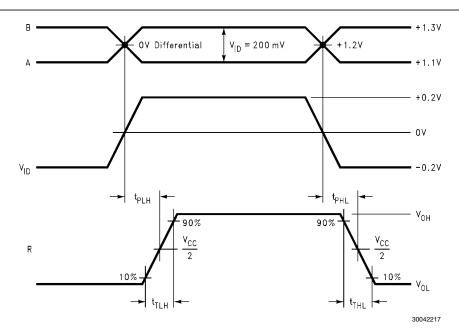


FIGURE 12. Type 1 Receiver Propagation Delay and Transition Time Waveforms

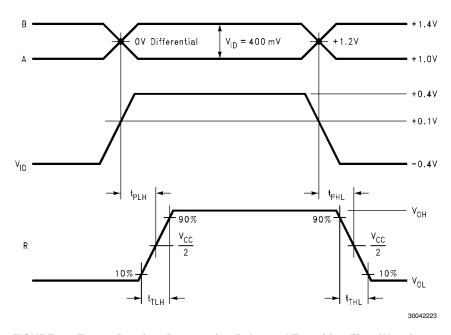


FIGURE 13. Type 2 Receiver Propagation Delay and Transition Time Waveforms

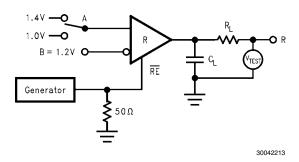


FIGURE 14. Receiver TRI-STATE Delay Test Circuit

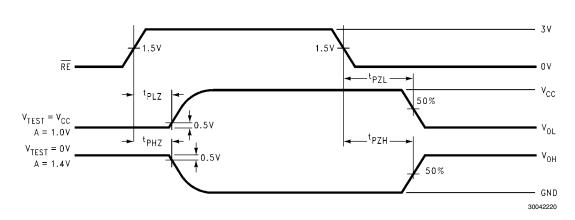


FIGURE 15. Receiver TRI-STATE Delay Waveforms

## **Truth Tables**

#### **DS91M040 Transmitting**

Inputs			Outputs		
RE	DE	DI	В	Α	
Х	Н	Н	L	Н	
Х	Н	L	Н	L	
Х	L	Х	Z	Z	

#### DS91M040 as Type 1 Receiving

	Inputs			
FSEN	RE	DE	A – B	RO
L	L	L	≥ +0.05V	Н
L	L	L	≤ -0.05V	L
L	L	L	0V	Χ
L	Η	L	Х	Z

#### DS91M040 as Type 2 Receiving

Inputs				Output
FSEN	RE	DE	A – B	R
Н	L	L	≥ +0.15V	Н
Н	L	L	≤ +0.05V	L
Н	L	L	0V	L
Н	Н	L	Х	Z

Don't care condition

#### DS91M040 Type 1 Receiver Input Threshold Test Voltages

Applied	Voltages	Resulting Differential Input Voltage	Resulting Common-Mode Input Voltage	Receiver Output
VIA	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>ICM</sub>	R
2.400V	0.000V	2.400V	1.200V	Н
0.000V	2.400V	-2.400V	1.200V	L
3.800V	3.750V	0.050V	3.775V	н
3.750V	3.800V	-0.050V	3.775V	L
-1.350V	-1.400V	0.050V	–1.375V	Н
-1.400V	-1.350V	-0.050V	–1.375V	L

H — High Level L — Low Level

#### DS91M040 Type 2 Receiver Input Threshold Test Voltages

Applied Voltages		Resulting Differential Input Voltage	Resulting Common-Mode Input Voltage	Receiver Output
V <sub>IA</sub>	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>IC</sub>	R
2.400V	0.000V	2.400V	1.200V	Н
0.000V	2.400V	-2.400V	1.200V	L
3.800V	3.650V	0.150V	3.725V	Н
3.800V	3.750V	0.050V	3.775V	L
-1.250V	-1.400V	0.150V	-1.325V	Н
-1.350V	-1.400V	0.050V	-1.375V	L

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X — Don't care condition

Z — High impedance state

X — Don't care condition Z — High impedance state

Z — High impedance state

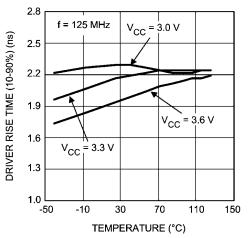
Output state assumes that the receiver is enabled  $(\overline{RE} = L)$ 

H — High Level

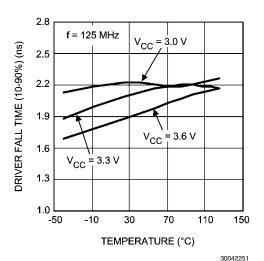
L — Low Level

Output state assumes that the receiver is enabled  $(\overline{RE} = L)$ 

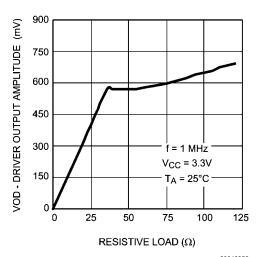
# **Typical Performance**



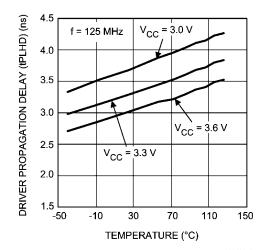
Driver Rise Time as a Function of Temperature



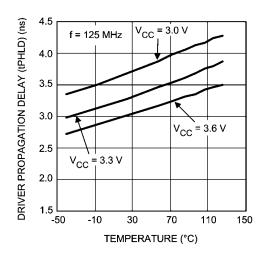
**Driver Fall Time as a Function of Temperature** 



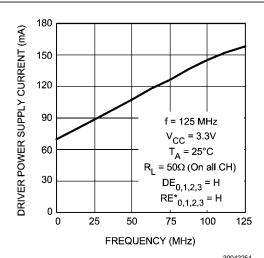
Driver Output Signal Amplitude as a Function of Resistive Load



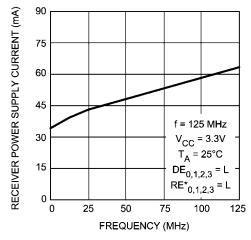
Driver Propagation Delay (tPLHD) as a Function of Temperature



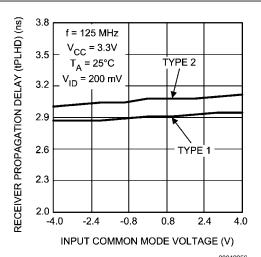
Driver Propagation Delay (tPHLD) as a Function of Temperature



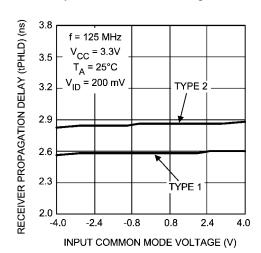
Driver Power Supply Current as a Function of Frequency



Receiver Power Supply Current as a Function of Frequency

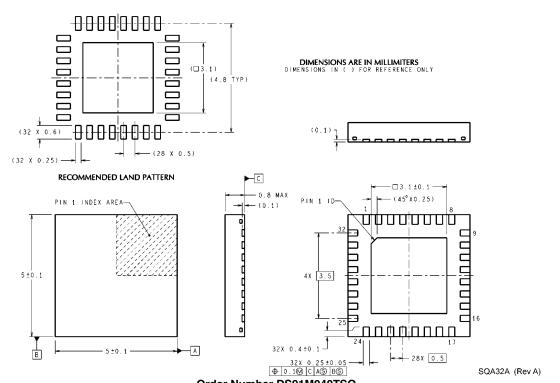


Receiver Propagation Delay (tPLHD) as a Function of Input Common Mode Voltage



Receiver Propagation Delay (tPHLD) as a Function of Input Common Mode Voltage

# Physical Dimensions inches (millimeters) unless otherwise noted



Order Number DS91M040TSQ
See NS package Number SQA32A
(See AN-1187 for PCB Design and Assembly Recommendations)

## **Notes**

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